

## 1. General description

Ultrafast power diode in a SOD142 (2-lead TO247) plastic package.

## 2. Features and benefits

- Fast switching
- Very low on-state loss
- Low leakage current
- Low thermal resistance

## 3. Applications

- Active PFC in air conditioner
- S.M.P.S Power Factor Correction (PFC)
- Half-bridge / full-bridge switched-mode power supplies

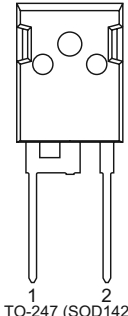

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
<b>Absolute maximum rating</b>						
$V_{RRM}$	repetitive peak reverse voltage		600			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 129\text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	30			A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 129\text{ }^{\circ}\text{C}$ ; square-wave pulse	60			A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>	290			A
		$t_p = 8.3\text{ ms}$ ; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; sine-wave pulse;	330			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward voltage	$I_F = 30\text{ A}$ ; $T_j = 25\text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 6</a>	-	1.18	1.55	V
		$I_F = 30\text{ A}$ ; $T_j = 150\text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 6</a>	-	0.98	-	V
<b>Dynamic characteristics</b>						
$t_{rr}$	reverse recovery time	$I_F = 1\text{ A}$ ; $V_R = 30\text{ V}$ ; $di_F/dt = 50\text{ A}/\mu\text{s}$ ; $T_j = 25\text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 7</a>	-	42	75	ns
		$I_F = 30\text{ A}$ ; $V_R = 400\text{ V}$ ; $di_F/dt = 200\text{ A}/\mu\text{s}$ ; $T_j = 25\text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 7</a>	-	65	-	ns
		$I_F = 30\text{ A}$ ; $V_R = 400\text{ V}$ ; $di_F/dt = 200\text{ A}/\mu\text{s}$ ; $T_j = 125\text{ }^{\circ}\text{C}$ ; <a href="#">Fig. 7</a>	-	101	-	ns

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-247 (SOD142)</p>	 001aaa020
2	A	anode		
mb	mb	mounting base; connected to cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BYV30W-600P	TO-247	Plastic Single-ended through-hole package; Heatsink mounted; 1 mounting hole; 2-lead TO-247	SOD142

## 7. Marking

Table 4. Marking codes

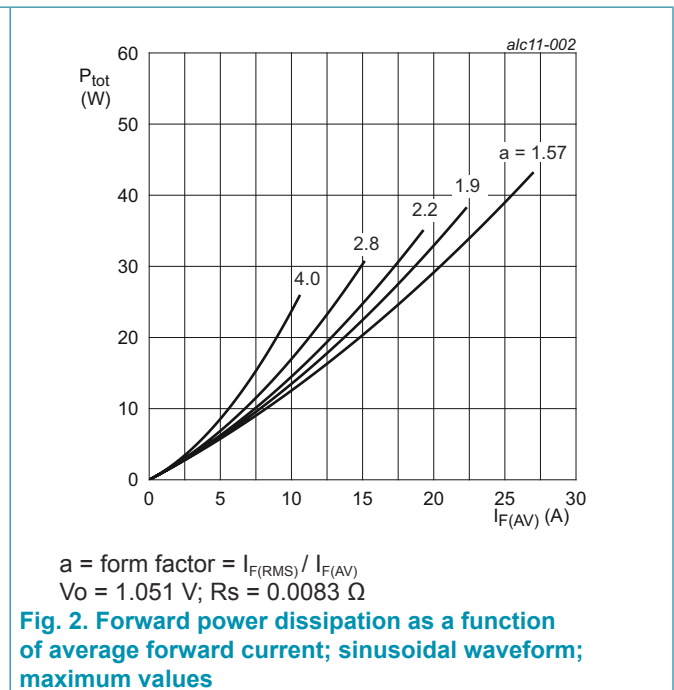
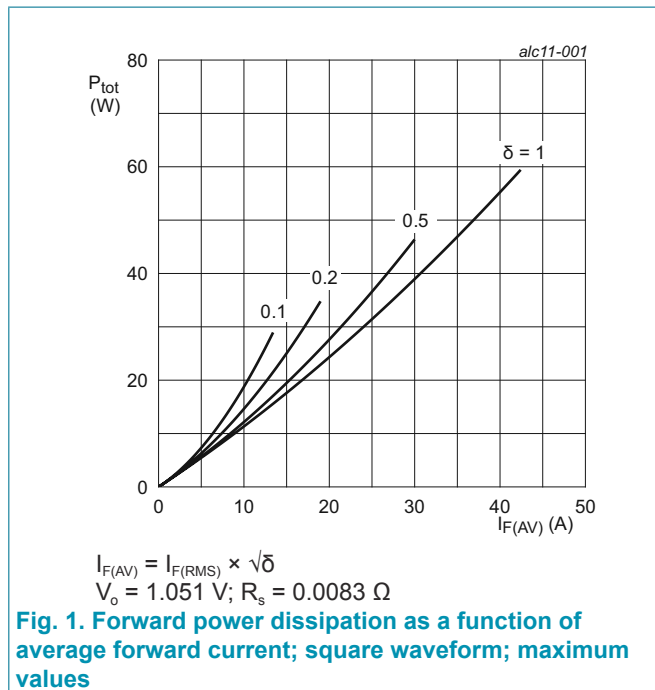
Type number	Marking codes
BYV30W-600P	BYV30W-600P

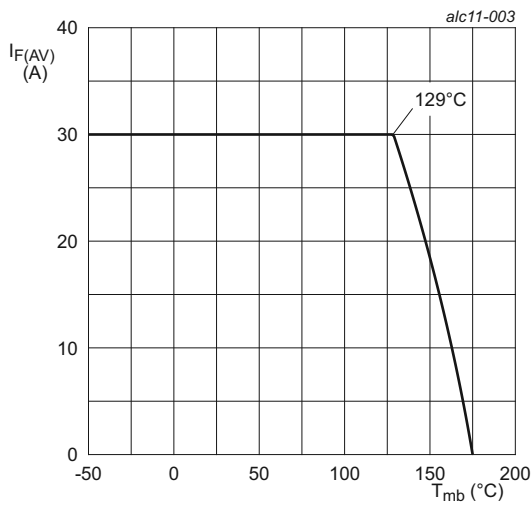
## 8. Limiting values

**Table 5. Limiting values**

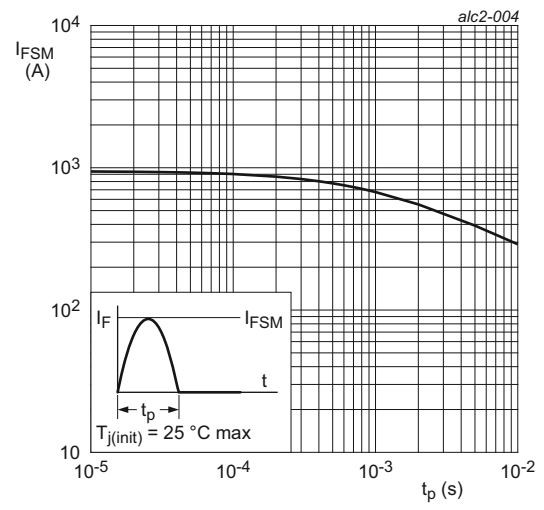
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		600	V
$V_{RWM}$	crest working reverse voltage		600	V
$V_R$	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_{mb} \leq 129\text{ }^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	30	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_{mb} \leq 129\text{ }^\circ\text{C}$ ; square-wave pulse	60	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse; <a href="#">Fig. 4</a>	290	A
		$t_p = 8.3\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; sine-wave pulse;	330	A
$T_{stg}$	storage temperature		-55 to 175	$^\circ\text{C}$
$T_j$	junction temperature		175	$^\circ\text{C}$





**Fig. 3. Forward current as a function of mounting base temperature; maximum values**



**Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values**

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>	-	-	1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	45	-	K/W

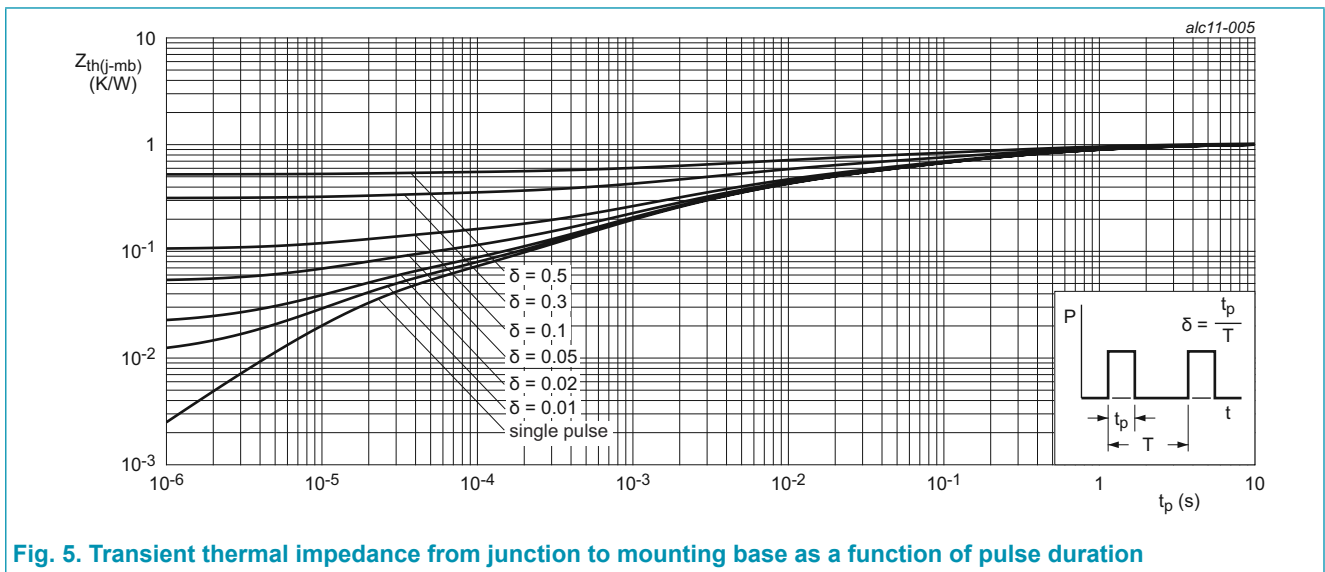
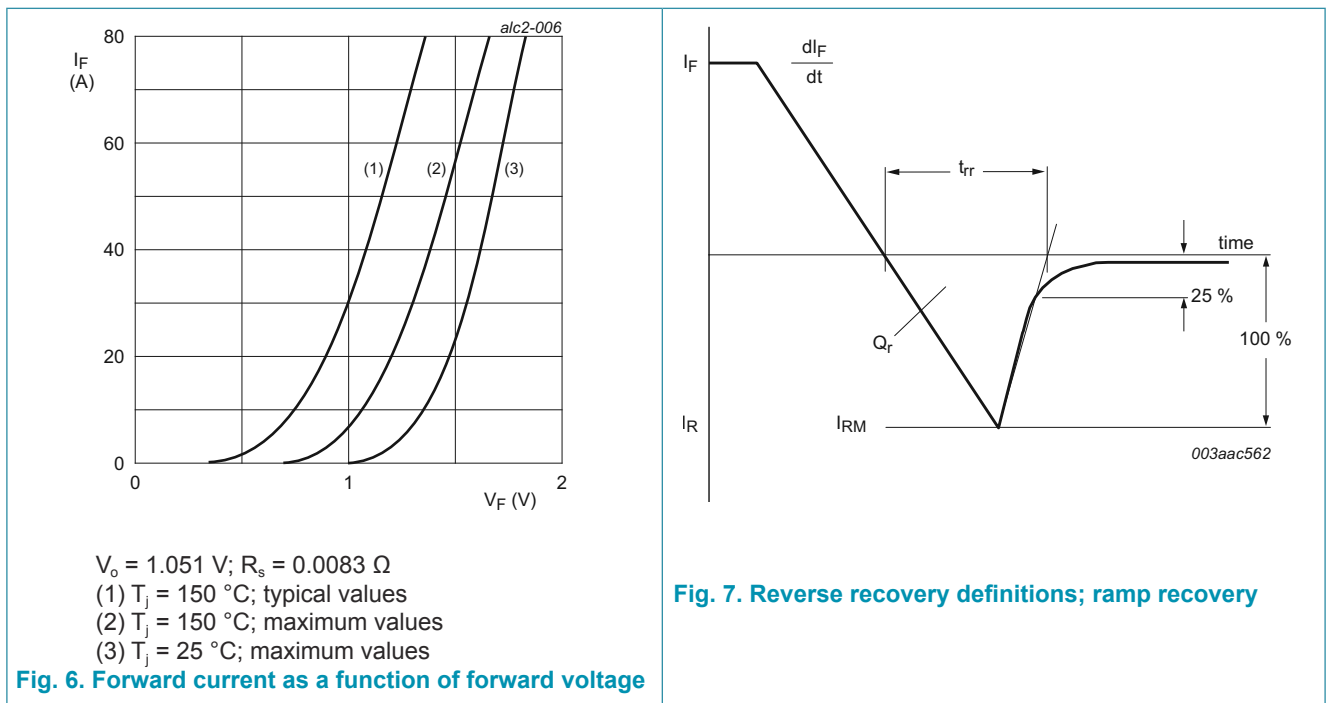


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

### 10. Characteristics

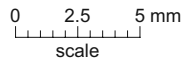
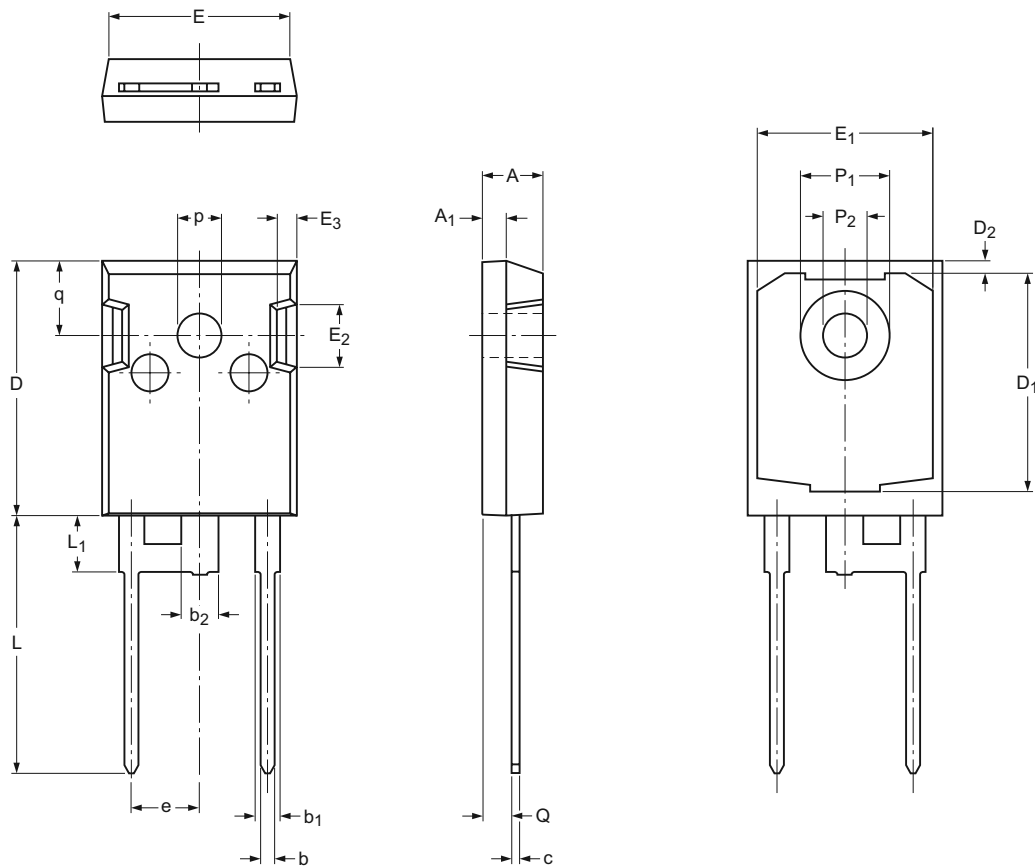
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F$	forward current	$I_F = 30 \text{ A}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 6}$	-	1.18	1.55	V
		$I_F = 30 \text{ A}; T_j = 150 \text{ }^\circ\text{C}; \text{Fig. 6}$	-	0.98	-	V
$I_R$	reverse current	$V_R = 600 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	2	10	$\mu\text{A}$
		$V_R = 600 \text{ V}; T_j = 125 \text{ }^\circ\text{C}$	-	-	500	$\mu\text{A}$
<b>Dynamic characteristics</b>						
$Q_r$	reverse charge	$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	272	-	nC
		$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	775	-	nC
$t_{rr}$	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	42	75	ns
		$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	65	-	ns
		$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	101	-	ns
$I_{RM}$	peak reverse recovery current	$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	8.4	-	A
		$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	15.2	-	A



### 11. Package outline

Plastic Single-ended through-hole package; Heatsink mounted; 1 mounting hole; 2-lead TO-247 SOD142



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	b	b <sub>1</sub>	b <sub>2</sub>	c	D	D <sub>1</sub>	D <sub>2</sub>	e	E	E <sub>1</sub>	E <sub>2</sub>	E <sub>3</sub>	L	L <sub>1</sub>	p	p <sub>1</sub>	p <sub>2</sub>	q	Q	
max	5.2	2.1	1.4	2.2	3.2	0.7	20.6	17.68	1.2	5.45	15.75	14.22	5.2	1.8	20.9	4.75	3.7	7.3	3.6	6.18	2.6	
nom																						
min	4.7	1.9	1.0	1.8	2.8	0.5	20.3	17.28	0.8		15.45	13.82	4.8	1.4	20.4	4.25	3.5	7.1	3.4	5.78	2.2	

sod142\_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOD142		TO247				12-11-13 12-11-27

Fig. 8. Package outline SOD142

## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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